

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application.

**Listing of Claims:**

1-11. (canceled)

12-20. (canceled)

21 (new). A method of chemical mechanical polishing, comprising:

providing a semiconductor wafer;

providing a pedestal comprising a central hub, a ring and spokes connecting the ring to the central hub;

placing the semiconductor wafer on the pedestal such that a surface of the semiconductor wafer contacts only an upper surface of the ring and does not contact an upper surface of the spokes and an upper surface of the hub;

moving the pedestal in a vertical manner and affixing a second surface of the semiconductor wafer to a wafer handler wherein said second surface of said semiconductor wafer is opposite said first surface of said semiconductor wafer;

applying water from said ring to the first surface of the semiconductor wafer to push the semiconductor wafer from said ring during said affixing of said semiconductor wafer; and

processing the semiconductor using chemical mechanical polishing; and removing the semiconductor wafer from said wafer handler.

22 (new). The method of claim 21 further comprising cleaning the surface of the semiconductor wafer by applying water to the first surface of the semiconductor wafer at positions between the ring and the hub following said removing of said semiconductor wafer from said wafer handler.